

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	(connection and pad and aluminum and etch\$3 and stopper and film and alloy and laminat\$2 and uppermost and copper and gold and silver and paste and via and hole)".clm.."	US-PGPUB	OR	ON	2006/12/04 13:01
S1	1	10/717591	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/12/15 13:09
S2	2	"20010010627".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/12/14 09:02
S3	2	"20030218249".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/12/14 09:03
S4	12488	insulator adj3 silicon	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/12/15 13:05
S5	0	("55555555").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/12/15 13:07
S6	2	("6546789").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2005/12/15 13:07
S7	204573	silicon.ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/15 13:07
S8	35295	shinko	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/12/15 13:10
S9	124994	(PB or PCB or PWB or ((printed or circuit or wiring) with (board\$1 or substrate\$1))) and ("174"\$.ccls. or "361"\$.ccls. or "257"\$.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/16 06:35

## EAST Search History

S10	57	S9 and (pad or land or terminal or electrode) same (etch\$ near stop\$ near film) and ((Al or aluminum) and ((copper or Cu) near film) or ((gold or Au) near film) or ((silver or Ag) near film))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/16 07:13
S11	22	S9 and (pad or land or terminal or electrode) same (etch\$ near stop\$ near film) and (laser and ((copper or Cu) near film) or ((gold or Au) near film) or ((silver or Ag) near film))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/16 07:37
S12	2	"5960308".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/16 07:35
S13	26	S9 and (pad or land or terminal or electrode) same (etch\$ near stop\$ near film) and (laser and ((copper or Cu) near film) or ((gold or Au) near film) or ((silver or Ag) near film) or (conductive near paste))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/16 07:38
S14	4	S9 and (pad or land or terminal or electrode) same (etch\$ near stop\$ near film) and (laser and ((copper or Cu) near film) or ((gold or Au) near film) or ((silver or Ag) near film) or (conductive near paste))not S11	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/16 07:41
S15	46	S9 and (etch\$ near stop\$ near film) and (laser and ((copper or Cu) near film) or ((gold or Au) near film) or ((silver or Ag) near film) or (conductive near paste))not S11	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/12/16 08:04
S16	572030	"174"\$.ccls. or "361"\$.ccls. or "257"\$.ccls. or "438"\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/24 15:03
S17	55774	S16 and laser\$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 15:42
S18	2055	S16 and (stop\$4 adj film\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 15:04

## EAST Search History

S19	319	S17 and S18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 15:05
S20	61	S19 and @pd<"20020111"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 15:44
S21	82465	S16 and copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 15:42
S22	17382	S21 and S17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 15:43
S23	3955	S22 and (stop\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 17:56
S24	1197	S23 and @pd<"20020111"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 15:46
S25	9	("20010010627" "20010011767" "20030218249" "5960308").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 15:54
S26	2	"6608371".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 15:54
S27	19	("20020000327"   "20020048916"   "5401913"   "5594275"   "5682062"   "5861666"   "6020629"   "6028358"   "6093029"   "6188127"   "6236115").PN. OR ("6608371").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/24 16:18

## EAST Search History

S28	7	S27 and stop\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 16:32
S29	0	2001/0055730.pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 16:47
S30	2	"20010055730".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 16:47
S31	2217	174/260.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/04 12:53